

DR Filter 3500.0MHz
Part No: MP09415

Model: GDRF J3500J
Rev No: 1

A. MAXIMUM RATING:

Electrostatic Sensitive Device (ESD)

1. Input Power Level: 1W
2. Operating Temperature: -40°C to +85°C
3. Storage Temperature: -40°C to +85°C
4. Moisture Sensitive Level (MSL): 2a

B. ELECTRICAL CHARACTERISTICS:

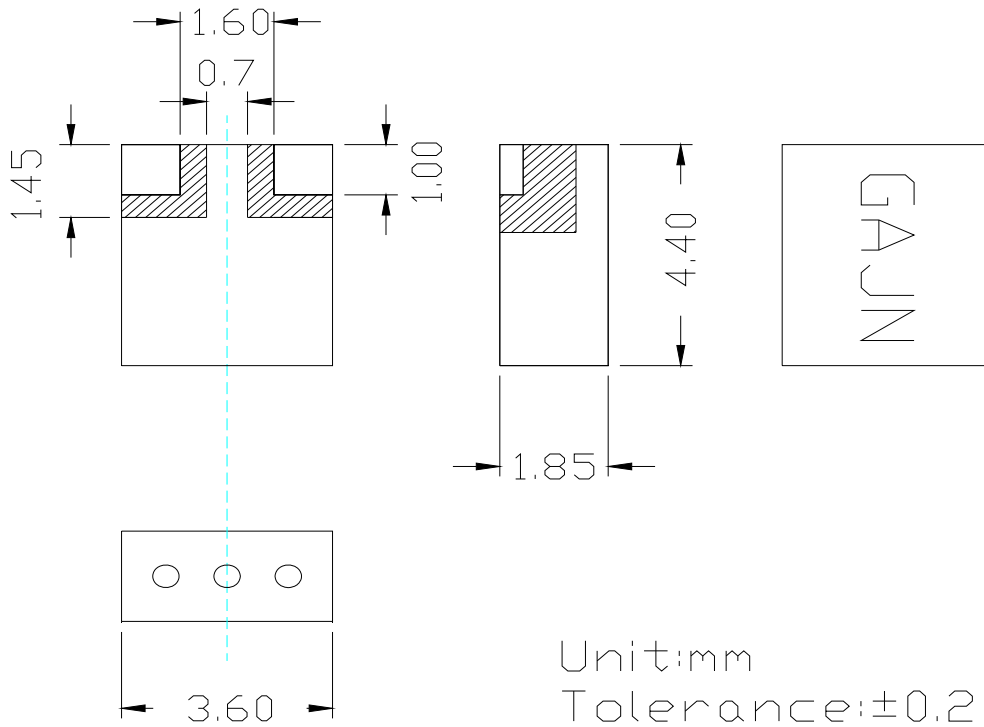
1. Terminating source impedance (single ended): $Z_S = 50\Omega$
2. Terminating load impedance (single ended): $Z_L = 50\Omega$

Item	Unit	Min	Typ	Max
Central Frequency Fc	MHz		3500	
Pass Band Width	MHz	200	200	
Pass Band Insertion loss	dB		2.0	2.5
Pass Band Ripple (fo ±12MHz)	dB		0.8	1.0
Pass Band Ripple (fo ±100MHz)	dB		1.2	1.5
Pass Band Return loss	dB	10	12	
Attenuation (Reference level from 0dB)				
3320MHz	dB	8		
3680MHz	dB	8		

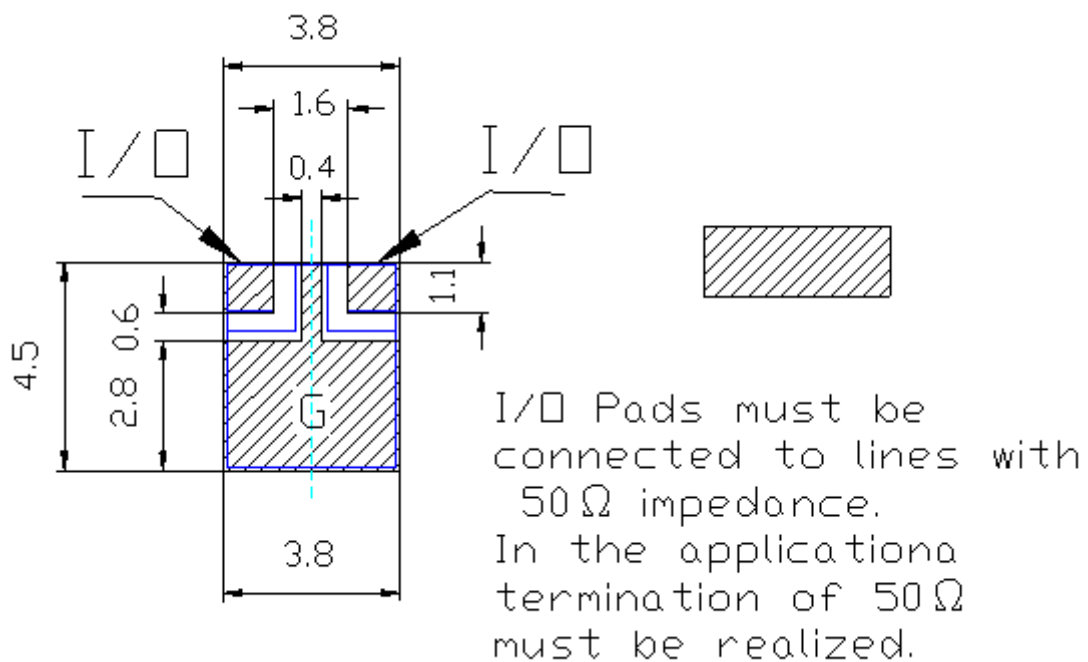
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C. OUTLINE DRAWING:



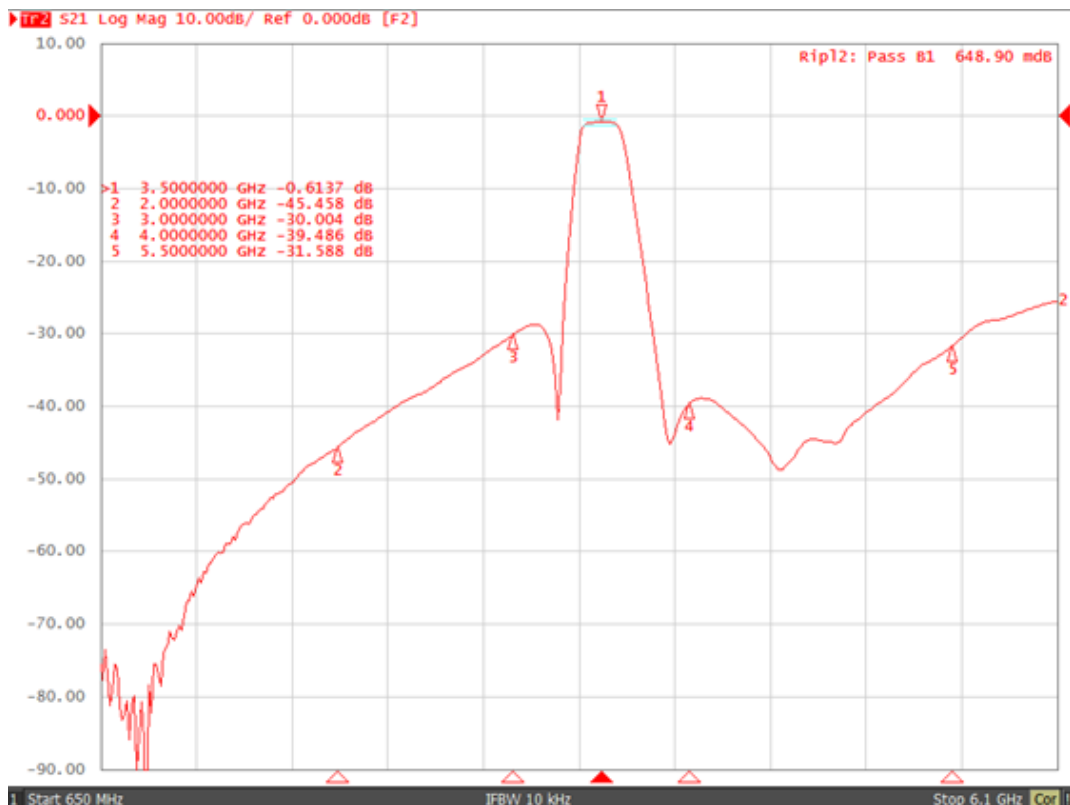
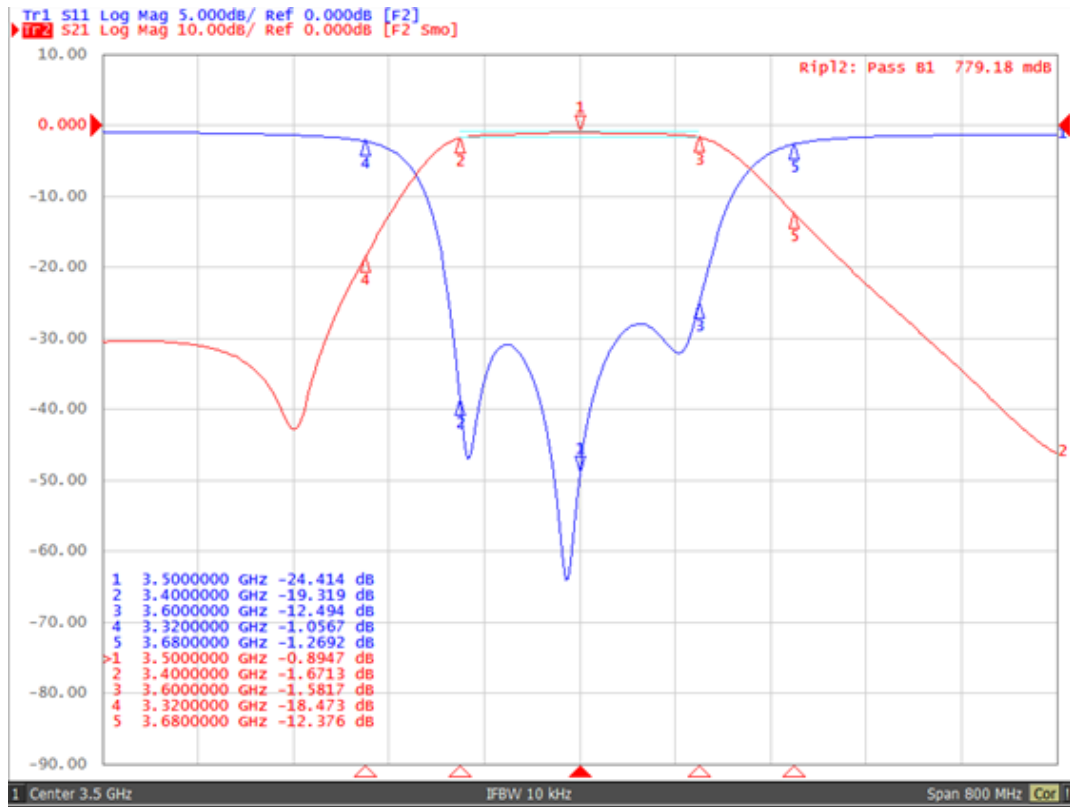
D. PCB FOOTPRINT:



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E. FREQUENCY CHARACTERISTICS:



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F. RECOMMENDED REFLOW PROFILE:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150°C 200°C 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3°C/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217°C 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260°C 3 second
RAMP-DOWN	Rate	6°C / second max.
Time from 25°C to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

The graphic shows temperature profile for component assembly process in reflow ovens

